SCLS027

SN54HC4514, SN74HC4514 4-LINE TO 16-LINE DECODERS/DEMULTIPLEXERS WITH ADDRESS LATCHES D2684, DECEMBER 1982-REVISED JUNE 1989

 Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

 Dependable Texas Instruments Quality and Reliability

description

These devices present two output options of a 4-line to 16-line decoder with latched inputs. The 'HC4514 presents a high level at the selected output.

These devices consist of four storage latches with common latch enable (LE) and inhibit (\overline{G}) inputs. When a low signal is applied to the LE input, the input data is stored, decoded, and presented to the output. When \overline{G} is high, all sixteen 'HC4514 outputs are at a low logic level.

The SN54HC4514 is characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN74HC4514 is characterized for operation from -40 °C to 85 °C.

FUNCTION	TABLE
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	1	NPU	тѕ			OUTPUT	OUTPUTS		
LE	G	D	С	В	Α	SELECTED	0019015		
н	L	L	L	L	٦	0			
н	Ł	L	L	L	н	1			
н	Ĺ	L	L	н	L	2			
н	L	٤	Ł	н	н	3			
н	L	L	н	L	L	4			
н	Ł	L	Н	L	н	5	Selected		
н	L	L	Н	н	L	6	Output = H		
H	Ł	L	н	н	н	7	All others = L		
н	L	н	L	L	L	8			
н	L	н	L	L	н	9			
н	L	н	L	н	L	10			
н	L	н	L	н	н	11			
н	L	н	н	L	L	12			
н	L	н	н	L	н	13			
н	L	н	Н	Н	L	14			
н	L	Н	н	н	н	15			
X	н	Х	Х	Х	Х		All = L		
L	Ĺ	x	х	x	х	All outputs remain in state existing before LEI			

SN54HC4514 . . . JT PACKAGE SN74HC4514 . . . DW OR NT PACKAGE (TOP VIEW) 23 🗌 Ğ A [2 22 🗌 D в 🛛 з Y7 ∏4 21 🛛 C Y6 🛛 5 20 Y 10 Y5 🗍6 19 Y11 Y4 🛛 7 18 🗍 Y 8 Y3 [8 17 Y9 Y1 🗍 9 16 Y14 Y2 []10 15 Y15 YO [11 14 Y12 GND [12 13 🗌 Y13

\$N54HC4514 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas instruments standard warrenty. Production processing does not necessarily include testing of all parameters.



logic symbols (alternatives)[†]

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¹These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, JT, and NT packages.



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logic diagram (positive logic)



Pin numbers shown are for DW, JT, and NT packages.



absolute maximum ratings over operating free-air temperature range[†]

Supply voltage, VCC
Input clamp current, IIK (VI < 0 or VI > VCC) ± 20 mA
Output clamp current, I_{OK} (VO < 0 or VO > VCC) ± 20 mA
Continuous output current, IQ (VO = 0 to VCC) $\dots \dots \dots$
Continuous current through VCC or GND pins ±50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or JT package
Lead temperature 1,6 mm (1/16 in) from case for 10 s: DW or NT package
Storage temperature range

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

			SN54HC4514			SN74HC4514			
			MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage		2	5	6	2	5	6	٧
	· · · · · · · · · · · · · · · · · · ·	$V_{CC} = 2 V$	1.5		4	1.5			
⊻н	High-level input voltage	$V_{CC} = 4.5 V$	3.15		Ē	3.15			V
		$V_{CC} = 6 V$	4.2		NEVIEW	4.2			
		V _{CC} = 2 V	0	6	0.3	0		0.3	
VII Lo	_ow-level input voltage	$V_{CC} = 4.5 V$	0	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	0.9	0		0.9	V
		$V_{CC} = 6 V$	0	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	1.2	0		1.2	
VI	Input voltage		0		Vcc	0		Vcc	- V
Vo	Output voltage		0	£	Vcc	0		Vcc	V
		V _{CC} = 2 V	0	~	1000	0		1000	
tt	Input transition (rise and fall) times	$V_{CC} = 4.5 V$	0		500	0		500	ns
•		V _{CC} = 6 V	0		400	0		400	
Тд	Operating free-air temperature		- 55		125	-40		85	°C

recommended operating conditions

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			T _A = 25°C			SN54HC4514		SN74HC4514		
PARAMETER	TEST CONDITIONS	Vcc	MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	
		2 V	1.9	1.998		1.9		1.9		
	$V_{I} = V_{IH}$ or V_{IL} , $I_{OH} = -20 \ \mu A$	4.5 V	4.4	4.499		4.4		4.4		
∨он		6 V	5.9	5.999		5.9		5.9		v
	$V_{I} = V_{IH}$ or V_{IL} , $I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.30		3.7	2	3.84		
	$V_{ } = V_{ }$ or $V_{ }$, $I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.80		5.2	<u>1</u>	5.34		
		2 V		0.002	0.1		∂ 0.1		0.1	
	$V_{i} = V_{iH}$ or V_{IL} , $I_{OL} = 20 \ \mu A$	4.5 V		0.001	0.1	6	0.1 0.1		0.1	
VOL		6 V		0.001	0.1	~	0.1		0.1	v
	$V_{I} = V_{IH} \text{ or } V_{IE}, I_{OL} = 4 \text{ mA}$	4.5 V		0.17	0.26	<u> </u>	0.4		0.33	
	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26	Γğ	0.4		0.33	
	$V_{I} = V_{CC} \text{ or } 0$	6 V		±0.1	±100	1.4	± 1000		± 1000	nA
ⁱ cc	$V_{I} = V_{CC} \text{ or } 0, I_{O} = 0$	6 V			8	_م_	160		80	μA
Ci		2 to 6 V		3	10		10		10	pF



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PARAMETER		Vee	Тд =	SN54HC4514		SN74HC4514			
	FARAWETER	Vcc	MIN MA		MIN	MAX	MIN	MAX	UNIT
		2 V	80		119		100	-	
tw	t _w Pulse duration, LE high	4.5 V	16		24	ź	20		ns
		6 V	14		20	VEW	17		
<u> </u>		2 V	100		149	a de la	125		
tsu	Setup time, A thru D before LEI	4.5 ∨	20		30	<u> </u>	25		ns
		6 V	17		30	,	21		
		2 V	5			, <u> </u>	5		
t _h Hold t	Hold time, A thru D before LEI	4.5 V	5		0, 4 5		5		ns
		6 V	5		5		5		

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), CL = 50 pF (see Note 1)

PARAMETER	FROM	то	N	T _A = 25°C		SN54HC45	4 SN74	SN74HC4514		
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN MA	X MIN	MAX	UNIT
			2 V		115	230	34	3	290	
tpd	A thru D	Алу	4.5 V		23	46	6	9	58	ns
			6 V		20	39		7	49	
			2 V		115	230	PREV 5	3	290	
^t pd	LE	Any	4.5 V		23	46	🔬 6	9	58	ns
			6 V		20	39	5 گە	8	49	
			2 V		88	175	<u> </u>	1	221	
tpd	ច	Any	4.5 V	1	18	35	ୁସ ୭	2	44	ns
			6 V		15	30	ン つ つ し し つ つ の よ 4	4	37	
		1	2 V		38	75	11	0	95	
tt		Any	4.5 V		8	15	2	2	19	ns
			6 V		6	13	11	9	16	
Cpd	Powe	r dissipation capa	citance		No loa	d, TA =	25 °C	e	0 pF typ	

Note 1: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC4514DW	OBSOLETE	SOIC	DW	24	TBD	Call TI	Call TI
SN74HC4514NT	OBSOLETE	PDIP	NT	24	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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